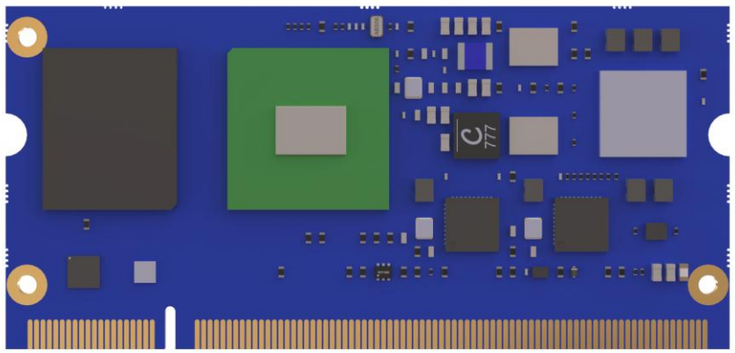
i.Core MX95

The new Engicam module for a wide range of edge applications from Automotive connectivity to Industry 4.0 and IoT platforms, is based on EDIMM 2.0 standard. i.Core MX95 is based on NXP® i.MX95 processor with 2.0 TOPS NPU, 3D GPU for advanced graphics, powerful vision and machine learning, real-time processing and security applications.



HIGHLIGHTS

- Standard EDIMM 2.0
- Powerful NXP ® i.MX95 processor with GPU, NPU and VPU
- Suitable for machine learning, vision and advanced multimedia applications

APPLICATIONS

Artificial Intelligence · Industrial · Digital Signage Infotainment · Transportation · Automotive · Avionics · Surveillance · Robotics · Biomedical/ Medical devices · Gaming · Home Automation

FEATURES

CPU	NXP® i.MX95
CORES	• 6x Arm Cortex-A55, up to 2.0 GHz • 1x Arm Cortex-M7, up to 800 MHz • 1x Arm Cortex-M33, up to 333 MHz
MEMORY	Up to 16GB (@ 6400 MT/s) LPDDR5
GRAPHICS	Arm Mali-G310 3D GPU supporting 50 GFLOPs FP32. • OpenGL® ES 3.2 • Vulkan® 1.3 • OpenCL 3.0
VIDEO INTERFACES	• LVDS • MIPI-DSI/CSI
VIDEO PROCESSING	• 4Kp60 H.265/H.264 decode and encode • 1x JPEG Encoder • 1x JPEG Decoder
AUDIO	• SAI Interface
NETWORKING	2x Gb Ethernet interfaces (1x RGMII option available)
USB	• 1x USB 3.0 • 1x USB 2.0
MASS STORAGE	Starting from 4GB eMMC drive soldered on-board
PERIPHERAL INTERFACES	UART, LPSPI, I²C, CAN Bus, GPIOs
PCIE	1x PCIe 3.0
OPERATING SYSTEM	• Linux Yocto • Android
POWER SUPPLY	+5V DC
DIMENSIONS	32 x 67,6 mm
OPERATING TEMPERATURE*	Extended Industrial qualified

* Valid for all components except CPU. Customer shall consider junction temperature for CPU. Temperature will widely depend on application. Specific cooling solutions could be necessary for the final system.

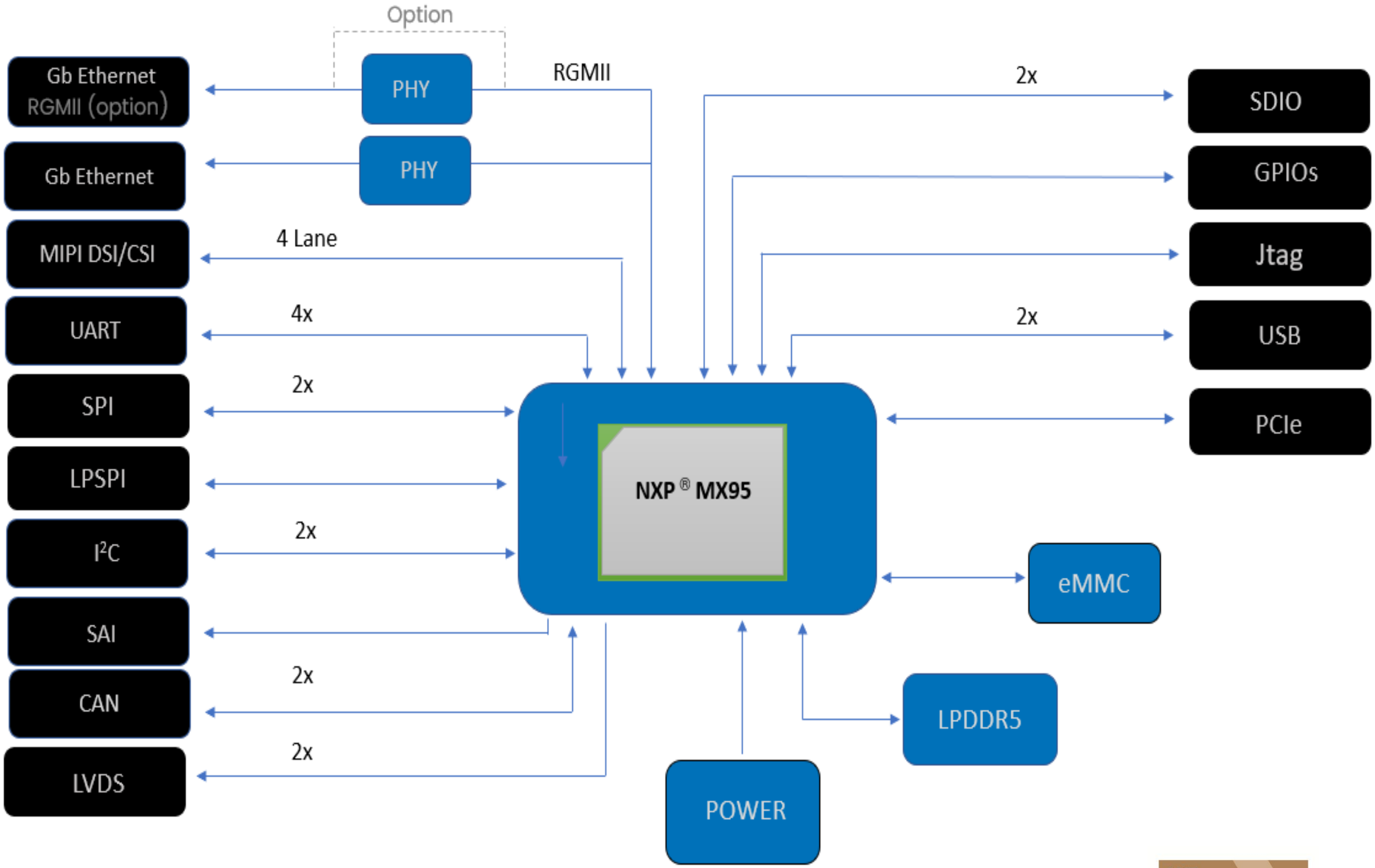
NXP Gold Partner

ENGICAM EMBEDDED SOLUTIONS

i.Core MX95

EDIMM2.0

BLOCK DIAGRAM



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